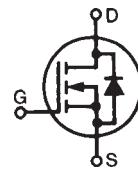


PolarHT™ Power MOSFET

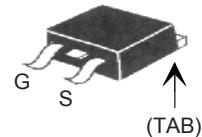
IXTA 42N25P
IXTP 42N25P
IXTQ 42N25P

V_{DSS} = 250 V
 I_{D25} = 42 A
 $R_{DS(on)}$ ≤ 84 mΩ

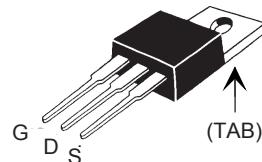
N-Channel Enhancement Mode
Avalanche Rated



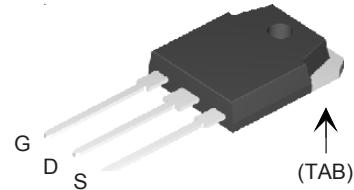
TO-263 (IXTA)



TO-220 (IXTP)



TO-3P (IXTQ)



G = Gate
S = Source

D = Drain
TAB = Drain

Symbol	Test Conditions	Maximum Ratings		
V_{DSS}	$T_J = 25^\circ C$ to $150^\circ C$	250	V	
V_{DGR}	$T_J = 25^\circ C$ to $150^\circ C$; $R_{GS} = 1 M\Omega$	250	V	
V_{GS}	Continuous	± 20	V	
V_{GSM}	Transient	± 30	V	
I_{D25}	$T_c = 25^\circ C$	42	A	
I_{DM}	$T_c = 25^\circ C$, pulse width limited by T_{JM}	110	A	
I_{AR}	$T_c = 25^\circ C$	42	A	
E_{AR}	$T_c = 25^\circ C$	30	mJ	
E_{AS}	$T_c = 25^\circ C$	1.0	J	
dv/dt	$I_s \leq I_{DM}$, $di/dt \leq 100 A/\mu s$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$, $R_G = 10 \Omega$	10	V/ns	
P_D	$T_c = 25^\circ C$	300	W	
T_J		-55 ... +150	°C	
T_{JM}		150	°C	
T_{stg}		-55 ... +150	°C	
T_L	1.6 mm (0.062 in.) from case for 10 s	300	°C	
T_{SOLD}	Plastic body for 10 s	260	°C	
M_d	Mounting torque (TO-3P / TO-220)	1.13/10	Nm/lb.in.	
Weight	TO-3P TO-220 TO-263	5.5 4 3	g g g	

Symbol	Test Conditions ($T_J = 25^\circ C$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0 V$, $I_D = 250 \mu A$	250		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	3.0		5.5 V
I_{GSS}	$V_{GS} = \pm 20 V_{DC}$, $V_{DS} = 0$		± 100	nA
I_{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$		25 250	μA
$R_{DS(on)}$	$V_{GS} = 10 V$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu s$, duty cycle d ≤ 2 %		84	mΩ

Features

- International standard packages
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect

Advantages

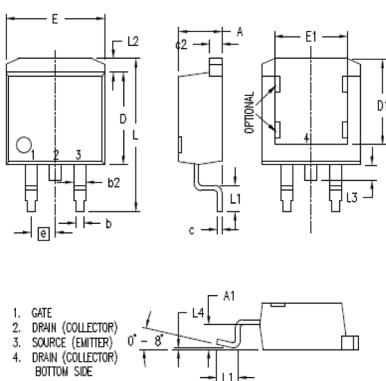
- Easy to mount
- Space savings
- High power density

Symbol **Test Conditions**
Characteristic Values
 $(T_J = 25^\circ C, \text{ unless otherwise specified})$
Min. **Typ.** **Max.**

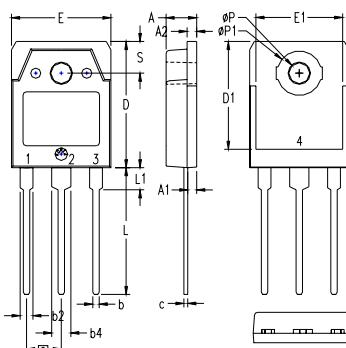
g_{fs}	$V_{DS} = 10 V; I_D = 0.5 I_{D25}$, pulse test	12	20	S
C_{iss} C_{oss} C_{rss}	$V_{GS} = 0 V, V_{DS} = 25 V, f = 1 \text{ MHz}$	2300	pF	
		430	pF	
		115	pF	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f	$V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$ $R_G = 10 \Omega$ (External)	24	ns	
		28	ns	
		81	ns	
		30	ns	
$Q_{g(on)}$ Q_{gs} Q_{gd}	$V_{GS} = 10 V, V_{DS} = 0.5 V_{DSS}, I_D = 0.5 I_{D25}$	70	nC	
		17	nC	
		37	nC	
R_{thJC}			0.42	°C/W
R_{thcs}	(TO-3P)	0.21		°C/W
	(TO-220)	0.25		°C/W

Source-Drain Diode
Characteristic Values
 $(T_J = 25^\circ C, \text{ unless otherwise specified})$

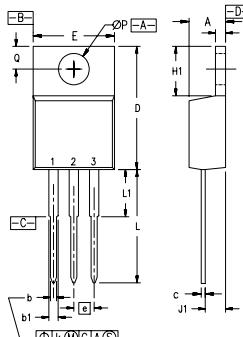
Symbol	Test Conditions	Min.	Typ.	Max.
I_s	$V_{GS} = 0 V$			42 A
I_{SM}	Repetitive			110 A
V_{SD}	$I_F = I_s, V_{GS} = 0 V$, Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2\%$			1.5 V
t_{rr}	$I_F = 25 A$ $-di/dt = 100 A/\mu\text{s}$	200		ns
Q_{RM}	$V_R = 100 V$	2.0		μC

TO-263 (IXTA) Outline


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	100	BSC	2.54	BSC
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

TO-3P (IXTQ) Outline

 1 - GATE
 2 - DRAIN (COLLECTOR)
 3 - SOURCE (EMITTER)
 4 - DRAIN (COLLECTOR)

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.193	4.70	4.90
A1	.051	.059	1.30	1.50
A2	.057	.065	1.45	1.65
b	.035	.045	0.90	1.15
b2	.075	.087	1.90	2.20
b4	.114	.126	2.90	3.20
c	.022	.031	0.55	0.80
D	.780	.799	19.80	20.30
D1	.665	.677	16.90	17.20
E	.610	.622	15.50	15.80
E1	.531	.539	13.50	13.70
e	215	BSC	5.45	BSC
L	.779	.795	19.80	20.20
L1	.134	.142	3.40	3.60
øP	.126	.134	3.20	3.40
øP1	.272	.280	6.90	7.10
S	.193	.201	4.90	5.10

TO-220 (IXTP) Outline


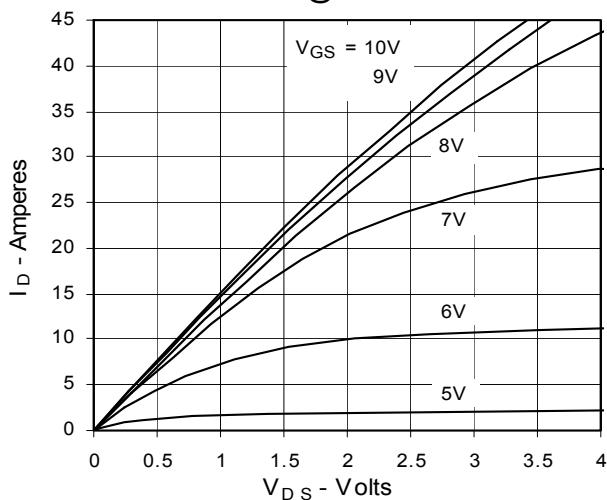
Pins: 1 - Gate 2 - Drain

SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	100	BSC	2.54	BSC
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
øP	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

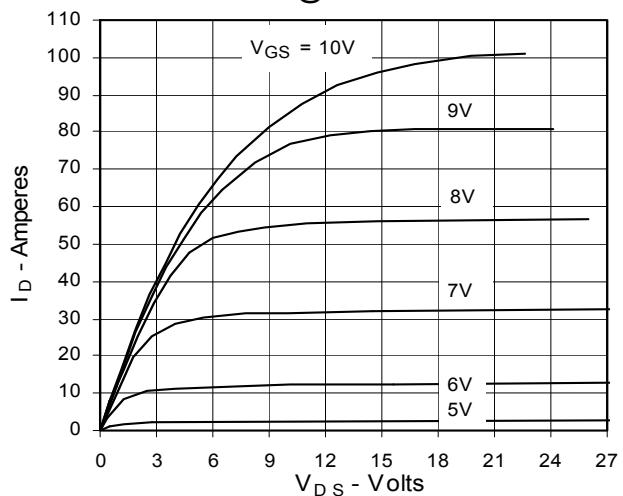
IXYS reserves the right to change limits, test conditions, and dimensions.

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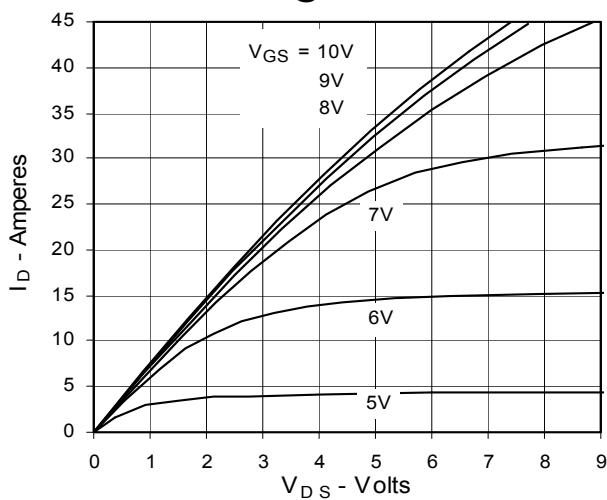
**Fig. 1. Output Characteristics
@ 25°C**



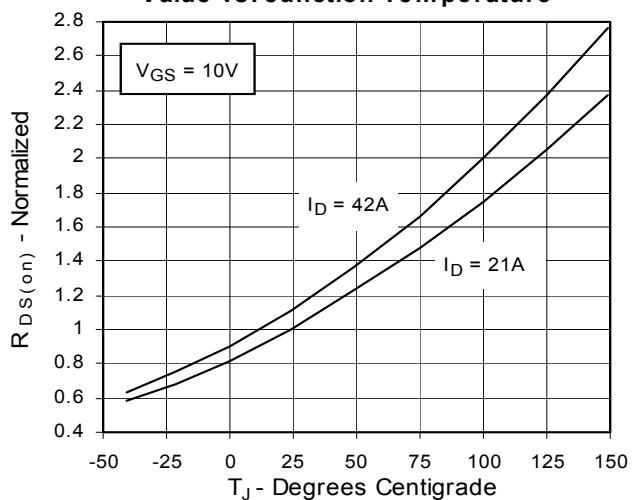
**Fig. 2. Extended Output Characteristics
@ 25°C**



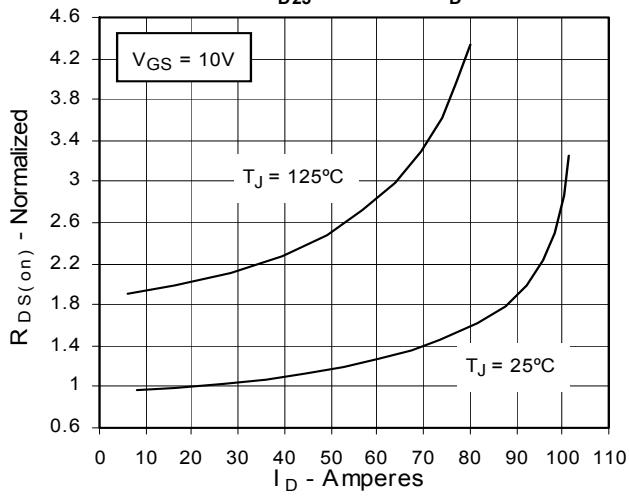
**Fig. 3. Output Characteristics
@ 125°C**



**Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25}
Value vs. Junction Temperature**



**Fig. 5. $R_{DS(on)}$ Normalized to
0.5 I_{D25} Value vs. I_D**



**Fig. 6. Drain Current vs. Case
Temperature**

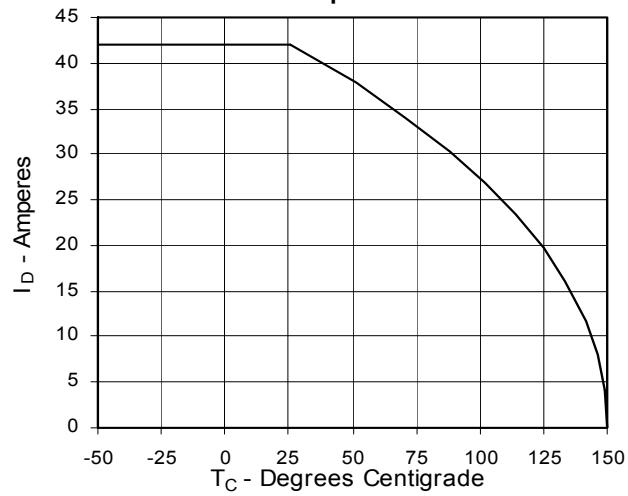


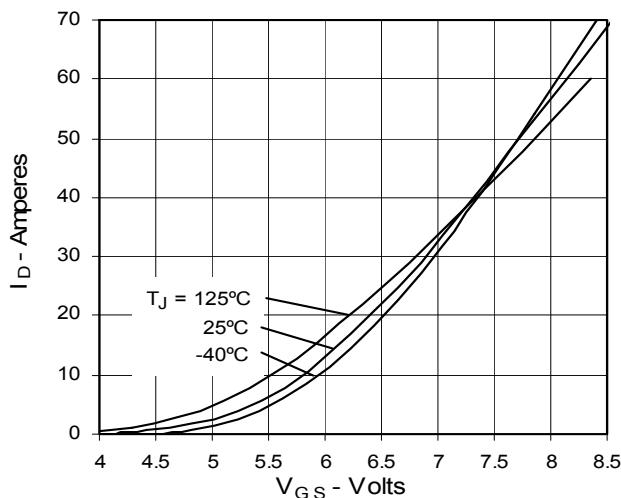
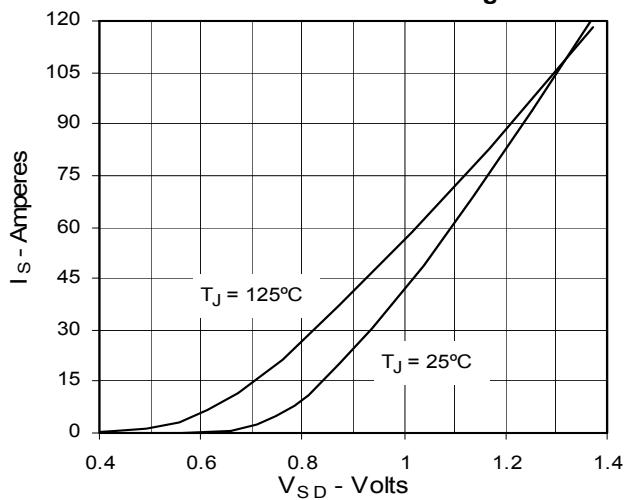
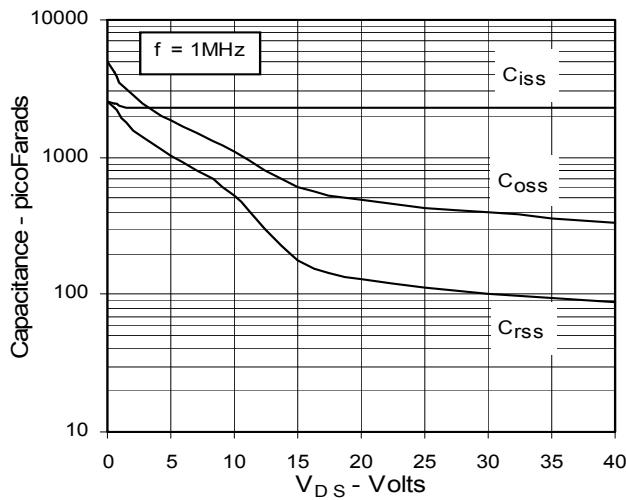
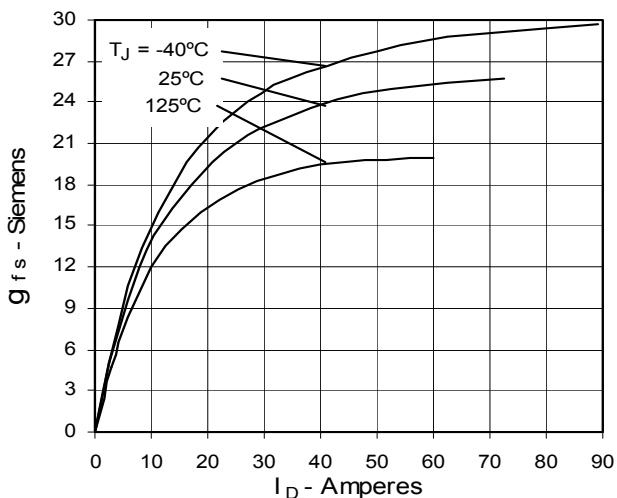
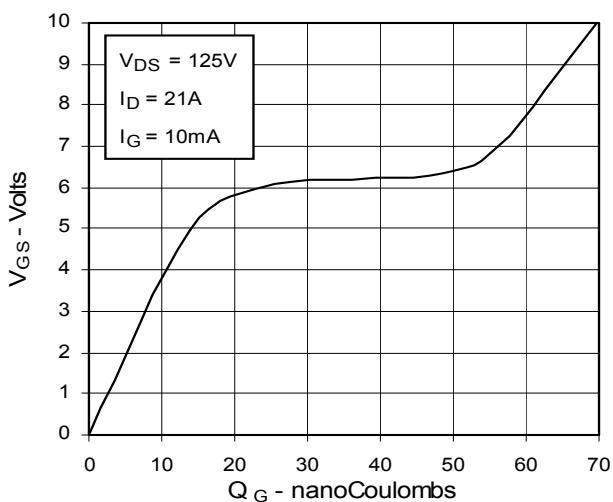
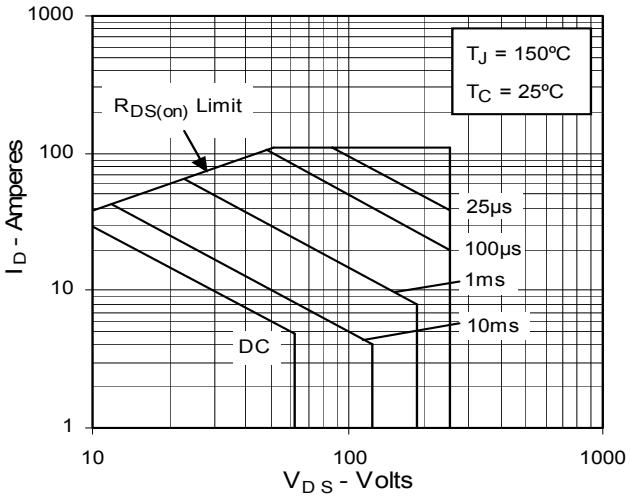
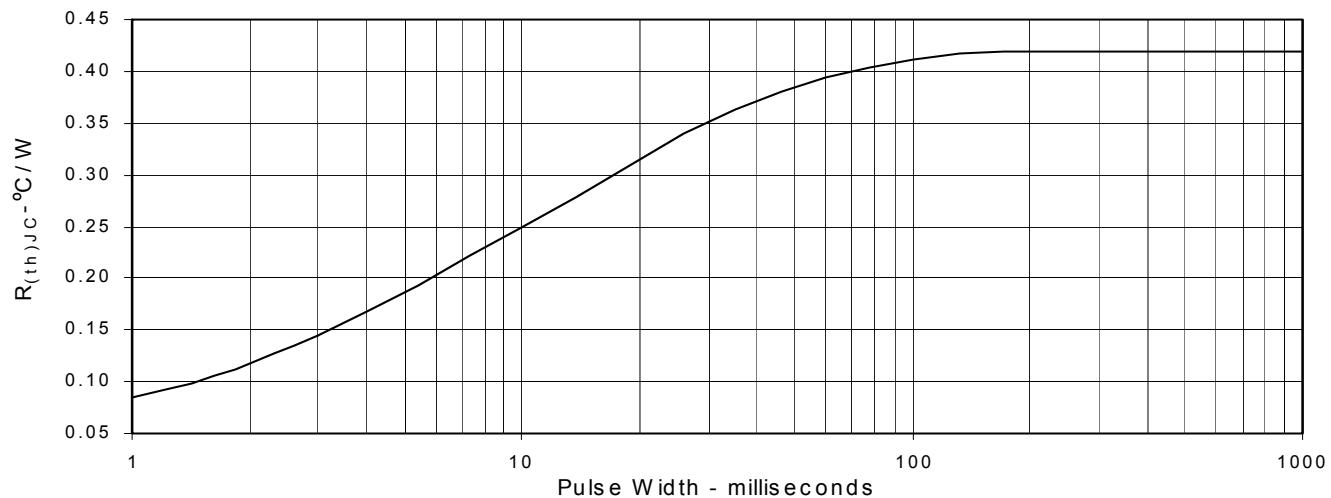
Fig. 7. Input Admittance

**Fig. 9. Source Current vs.
Source-To-Drain Voltage**

Fig. 11. Capacitance

Fig. 8. Transconductance

Fig. 10. Gate Charge

**Fig. 12. Forward-Bias
Safe Operating Area**


Fig. 13. Maximum Transient Thermal Resistance



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